

DMC1018UPD

COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET **POWERDI**

Product Summary

Device	V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = +25°C
Q1	12V	$17m\Omega @ V_{GS} = 4.5V$	9.5A
Qi	. = .	$25m\Omega$ @ $V_{GS} = 2.5V$	7.8A
Q2	201/	$32m\Omega$ @ $V_{GS} = -4.5V$	-6.9A
	-20V	Q2 -20V	53mΩ @ V _{GS} = -2.5V

Description and Applications

This new generation Complementary Pair Enhancement Mode MOSFET has been designed to minimize $R_{\text{DS}(\text{ON})}$ and yet maintain superior switching performance. This device is ideal for use in Notebook battery power management and Loadswitch.

- Notebook Battery Power Management
- **DC-DC Converters**

Top View

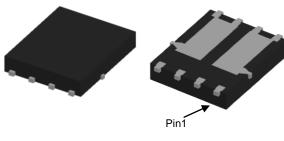
Loadswitch

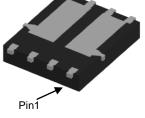
Features and Benefits

- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

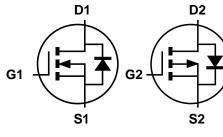
Mechanical Data

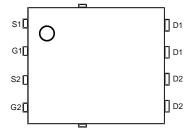
- Case: PowerDI5060-8 (Type C)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish 100% Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Terminal Connections: See Diagram Below
- Weight: 0.097 grams (Approximate)





Bottom View





Q1 N-Channel MOSFET Q2 P-Channel MOSFET

Top View Pin Configuration

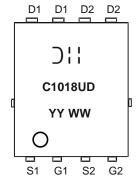
Ordering Information (Note 4)

Part Number	Case	Packaging	
DMC1018UPD-13	PowerDI5060-8 (Type C)	2500 / Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



⊃¦¦ = Manufacturer's Marking C1018UD = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 15 = 2015)WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Q1 Value	Q2 Value	Units		
Drain-Source Voltage	V _{DSS}	12	-20	V		
Gate-Source Voltage	V _{GSS}	±8	±12	V		
Continuous Drain Current (Note EVV 4 EV	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	9.5 7.6	-6.9 -5.5	А
Continuous Drain Current (Note 5) V _{GS} = 4.5V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	I _D	13.0 10.4	-9.4 -7.5	Α
Maximum Body Diode Forward Current (Note 5)	I _S	2.5	-2.5	Α		
Pulsed Drain Current (10µs pulse, duty cycle = 1	I _{DM}	60	-40	Α		
Avalanche Current (Note 6) L = 0.1mH	I _{AS}	20	-17	Α		
Avalanche Energy (Note 6) L = 0.1mH	E _{AS}	25	14	mJ		

Thermal Characteristics

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 5)	T _A = +25°C	D-	2.3	W
Total Fower Dissipation (Note 3)	T _A = +70°C	P_{D}	1.5	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	54	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{ heta JA}$	29	
Thermal Resistance, Junction to Case	$R_{ heta JC}$	6.5		
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics Q1 N-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage	BV _{DSS}	12	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$		
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μA	V _{DS} = 12V, V _{GS} = 0V		
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$		
ON CHARACTERISTICS (Note 7)	ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	0.6	0.8	1.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$		
Static Drain-Source On-Resistance	Dagger		8	17	mΩ	$V_{GS} = 4.5V, I_D = 11.8A$		
Static Brain-Source On-Nesistance	R _{DS(ON)}	_	11	25	11152	$V_{GS} = 2.5V, I_D = 9.8A$		
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_S = 2.9A$		
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	Ciss		1525			$V_{DS} = 6V, V_{GS} = 0V,$ f = 1.0MHz		
Output Capacitance	Coss		329	_	pF			
Reverse Transfer Capacitance	C _{rss}	_	303	_				
Gate Resistance	R_{G}	_	1.6	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$		
Total Gate Charge (V _{GS} = 4.5V)	Q_g	_	17.1	_		V 0V 1 44 0A		
Total Gate Charge (V _{GS} = 8V)	Q_g	_	30.4	_	nC			
Gate-Source Charge	Q_{gs}	_	2.6	_	110	$V_{DS} = 6V, I_{D} = 11.8A$		
Gate-Drain Charge	Q_{gd}	_	4.3	_				
Turn-On Delay Time	t _{D(ON)}	_	6.6	_		$V_{DD}=6V,R_L=6\Omega$ $V_{GS}=4.5V,R_G=6\Omega,I_D=1A$		
Turn-On Rise Time	t _R	_	10.8	_				
Turn-Off Delay Time	t _{D(OFF)}	_	41.5	_	ns			
Turn-Off Fall Time	t _F	_	21.9	_				
Body Diode Reverse Recovery Time	t _{RR}		14.3	_	ns	I _F = 11.8A, di/dt = 100A/μs		
Body Diode Reverse Recovery Charge	Q_{RR}	_	2.3	_	nC	$I_F = 11.8A$, $di/dt = 100A/\mu s$		



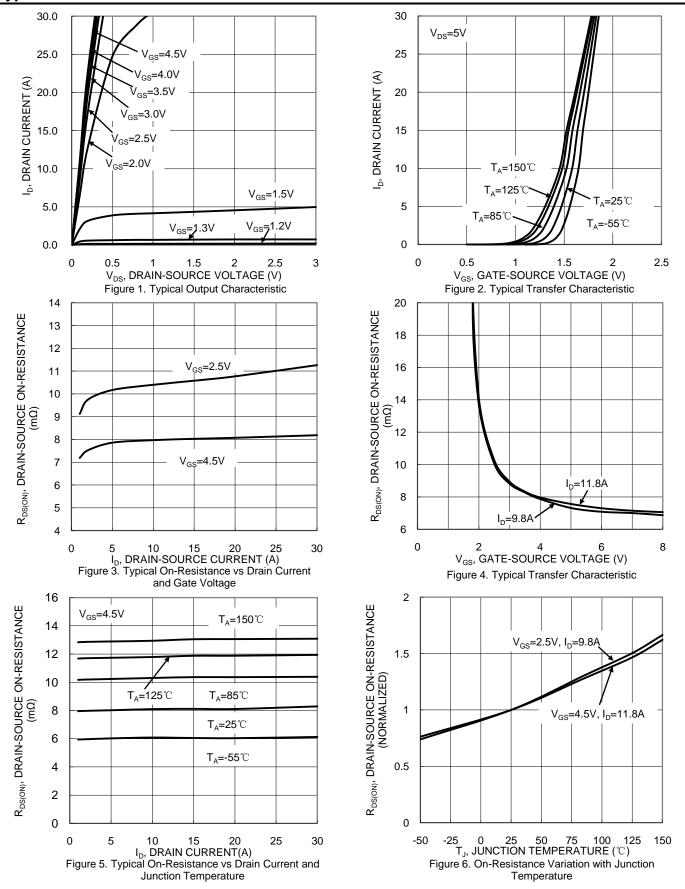
Electrical Characteristics Q2 P-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μA	$V_{DS} = -16V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	-0.6	-0.8	-1.5	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
Static Drain-Source On-Resistance	D	_	22	32	mΩ	$V_{GS} = -4.5V, I_{D} = -8.9A$	
Static Dialif-Source Off-Resistance	R _{DS(ON)}	_	31	53	11122	$V_{GS} = -2.5V, I_D = -6.9A$	
Diode Forward Voltage	V_{SD}		-0.7	-1.2	V	$V_{GS} = 0V, I_S = -2.9A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}		866			V _{DS} = -6V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	167	_	pF		
Reverse Transfer Capacitance	Crss	_	131	_			
Gate Resistance	R_{G}		4.9	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Q_g	_	8.6	_		Vps = -6V. Ip = -8.9A	
Total Gate Charge (V _{GS} = -8V)	Q_g	_	19	_	nC		
Gate-Source Charge	Qgs	_	1.5	_	110	VDS = -6V, ID = -6.9A	
Gate-Drain Charge	Q_{gd}	_	2.5	_			
Turn-On Delay Time	t _{D(ON)}	_	5.8	_		V_{DD} = -6V, R_L = 6 Ω V_{GS} = -4.5V, R_G = 6 Ω , I_D = -1A	
Turn-On Rise Time	t _R	_	7.7	_	ns		
Turn-Off Delay Time	t _{D(OFF)}	_	28.1	_	115		
Turn-Off Fall Time	t _F	_	14.6	_			
Body Diode Reverse Recovery Time	t _{RR}	_	9.8	_	ns	I _F = -8.9A, di/dt = -100A/μs	
Body Diode Reverse Recovery Charge	Q _{RR}	1	2.7	_	nC	$I_F = -8.9A$, $di/dt = -100A/\mu s$	

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. 6. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$. 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.

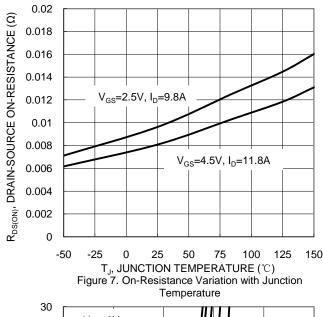


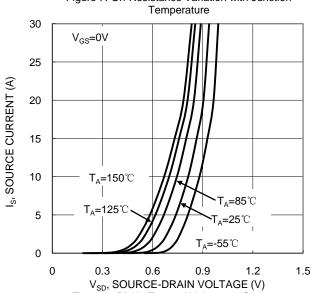
Typical Characteristics - N-CHANNEL

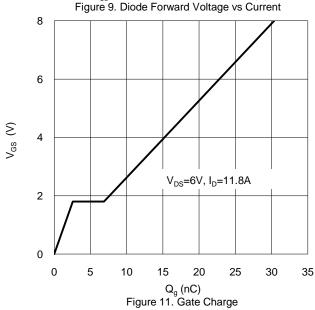


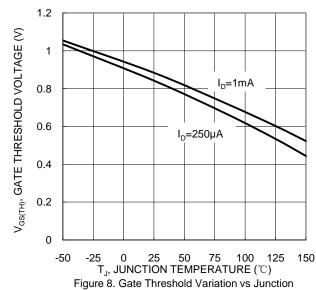


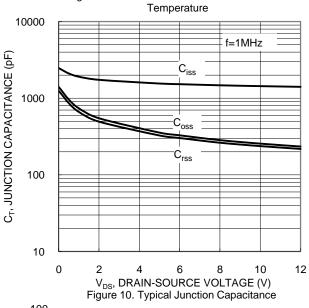


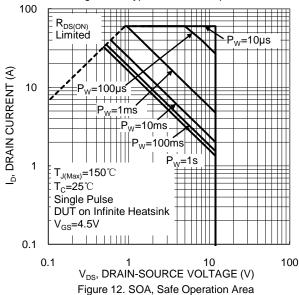






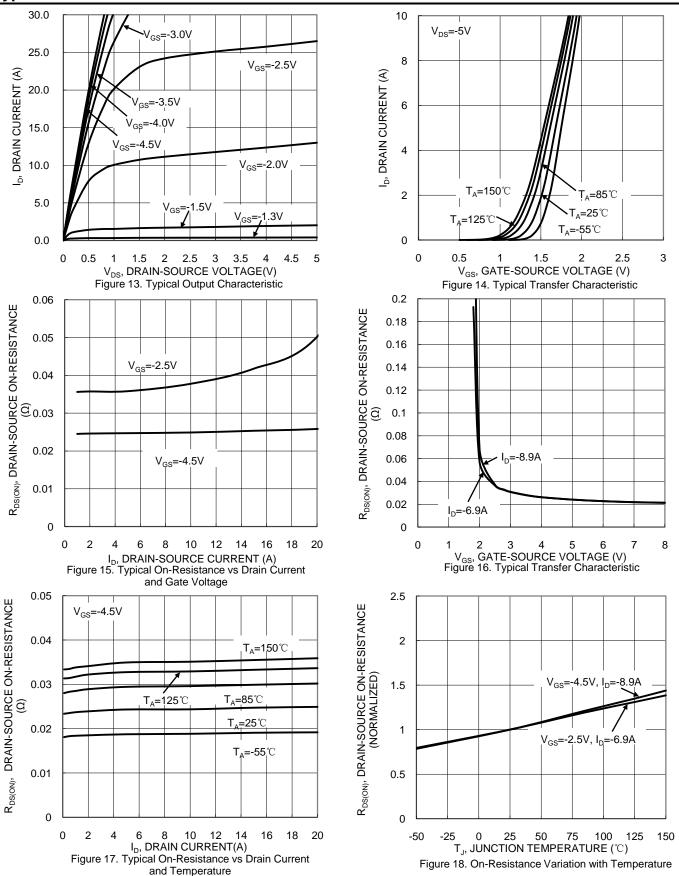






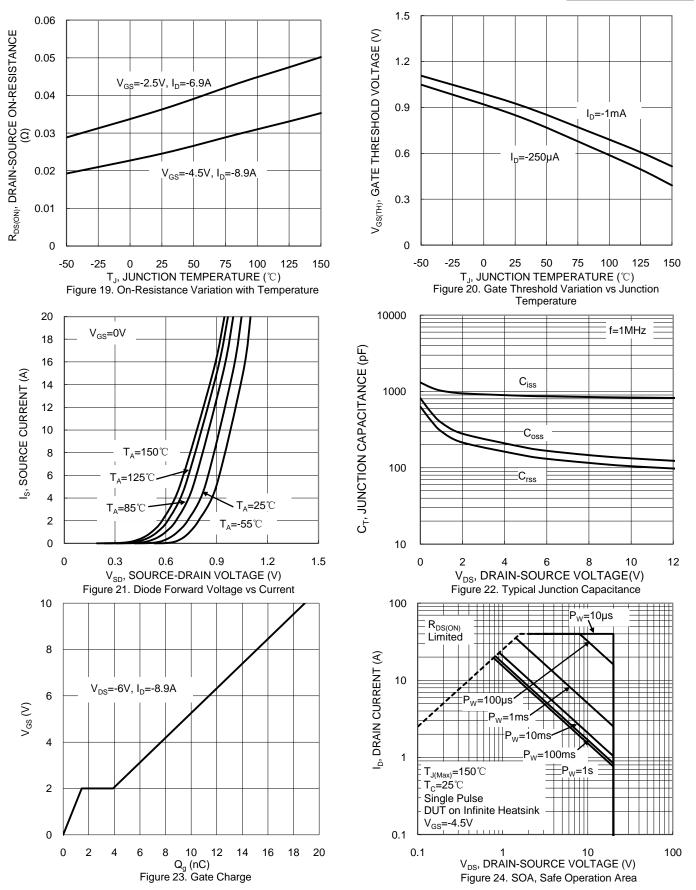


Typical Characteristics - P-CHANNEL











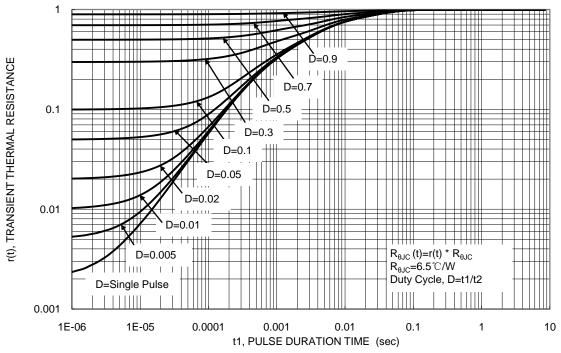


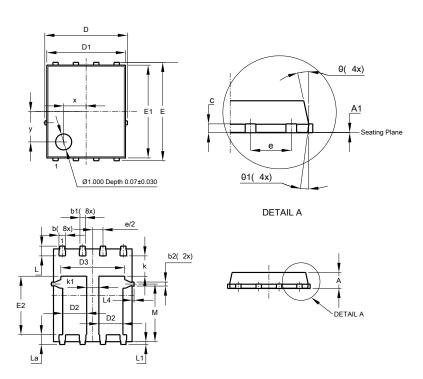
Figure 25. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (Type C)

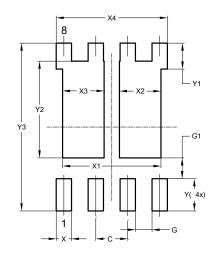


PowerDI5060-8 (Type C)						
Dim	Min	Max	Тур			
Α	0.90	1.10	1.00			
A1	0	0.05	0.02			
b	0.33	0.51	0.41			
b1	0.300	0.366	0.333			
b2	0.20	0.35	0.25			
С	0.23	0.33	0.277			
D	5	.15 BS0				
D1	4.85	4.95	4.90			
D2	1.40	1.60	1.50			
D3	-	-	3.98			
Е	6	.15 BS0				
E1	5.75	5.85	5.80			
E2	3.56	3.76	3.66			
е	1.27BSC					
k	-	-	1.27			
k1	0.56	-	-			
L	0.51	0.71	0.61			
La	0.51	0.71	0.61			
L1	0.05	0.20	0.175			
L4	-	-	0.125			
М	3.50	3.71	3.605			
Х	-	-	1.400			
у	-	-	1.900			
θ	10°	12°	11°			
θ1	6° 8° 7°					
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (Type C)



Dimensions	Value		
Difficusions	(in mm)		
С	1.270		
G	0.660		
G1	0.820		
Х	0.610		
X1	3.910		
X2	1.650		
Х3	1.650		
X4	4.420		
Υ	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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